

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

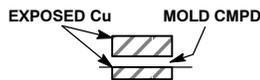
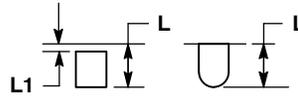
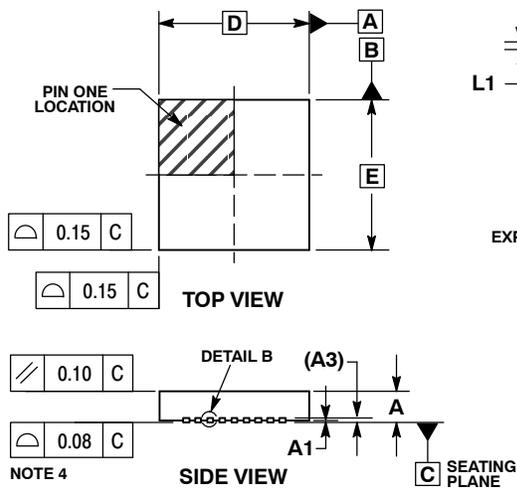


1 36

SCALE 2:1

QFN36 5x5, 0.4P
CASE 485CC
ISSUE O

DATE 29 NOV 2011

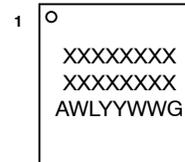


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSIONS: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

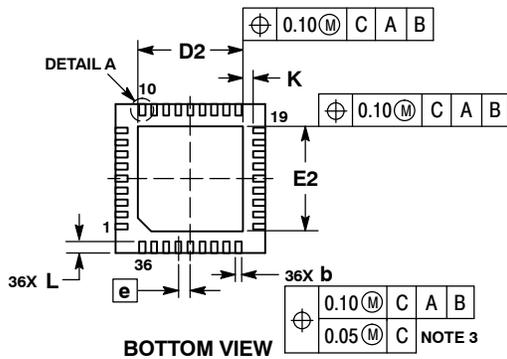
DIM	MILLIMETERS	
	MIN	MAX
A	0.80	1.00
A1	---	0.05
A3	0.20	REF
b	0.15	0.25
D	5.00	BSC
D2	3.40	3.60
E	5.00	BSC
E2	3.40	3.60
e	0.40	BSC
K	0.35	REF
L	0.30	0.50
L1	---	0.15

GENERIC MARKING DIAGRAM*

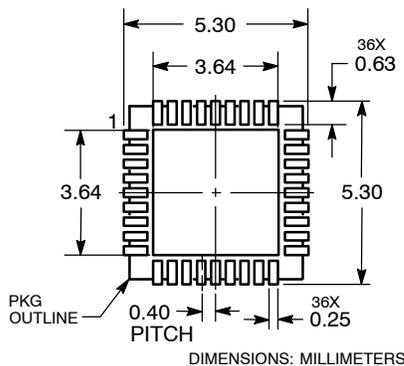


- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.



RECOMMENDED SOLDERING FOOTPRINT



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NEW STANDARD:		
DESCRIPTION:	QFN36, 5x5, 0.4P	PAGE 1 OF 2

